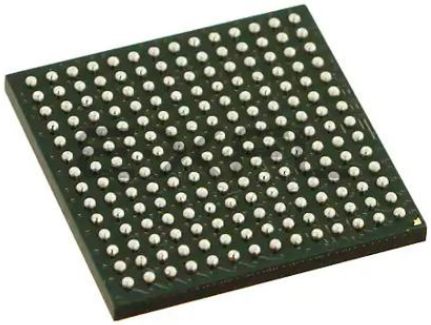


Welcome to E-XFL.COM

Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Obsolete
Type	Fixed Point
Interface	Host Interface, SSI, SCI
Clock Rate	150MHz
Non-Volatile Memory	ROM (576B)
On-Chip RAM	384kB
Voltage - I/O	3.30V
Voltage - Core	1.80V
Operating Temperature	-40°C ~ 100°C (TJ)
Mounting Type	Surface Mount
Package / Case	196-LBGA
Supplier Device Package	196-LBGA (15x15)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/dsp56311vl150b1

Signals/Connections 1

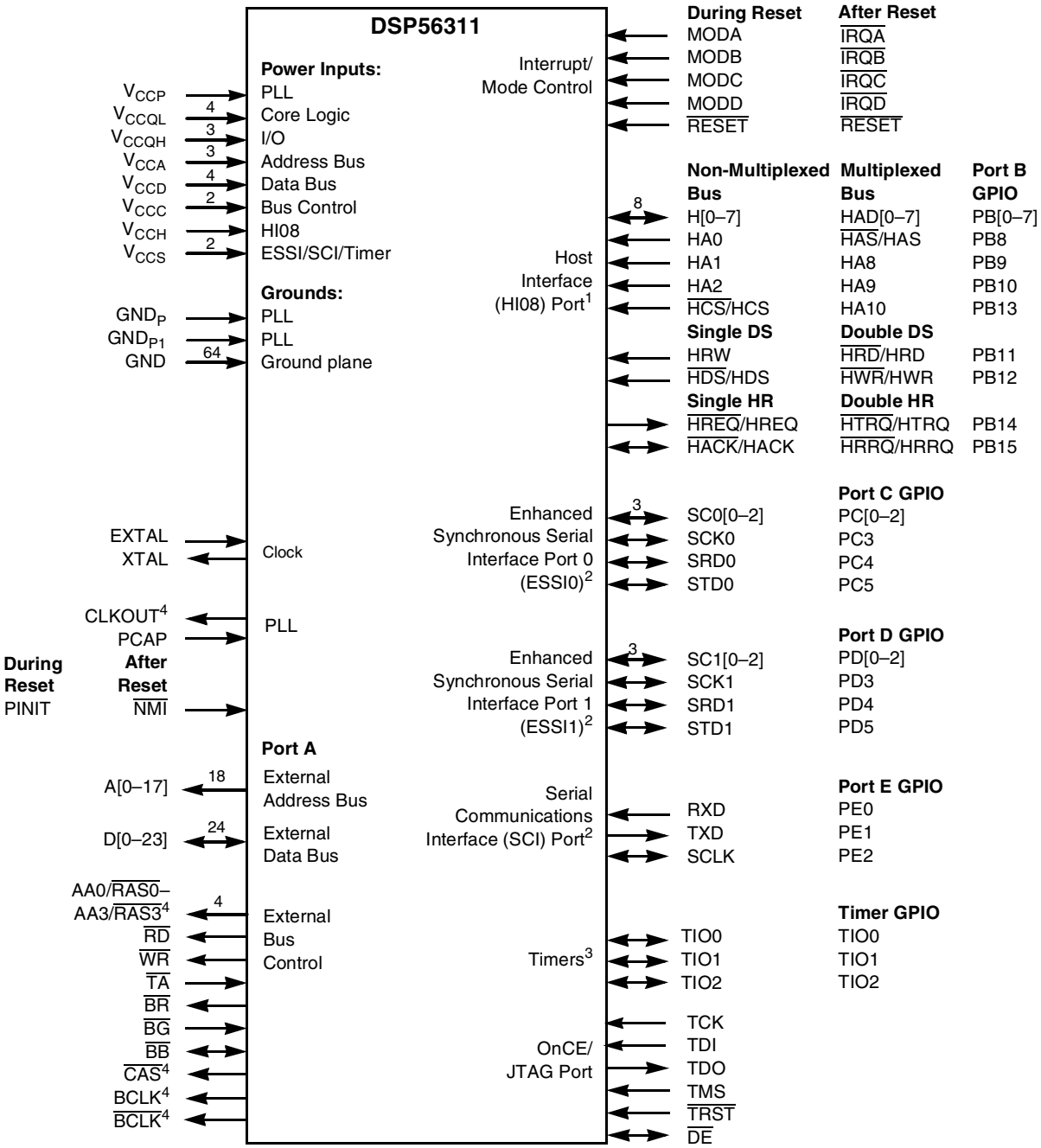
The DSP56311 input and output signals are organized into functional groups as shown in **Table 1-1**. **Figure 1-1** diagrams the DSP56311 signals by functional group. The remainder of this chapter describes the signal pins in each functional group.

Table 1-1. DSP56311 Functional Signal Groupings

Functional Group		Number of Signals
Power (V_{CC})		20
Ground (GND)		66
Clock		2
PLL		3
Address bus	Port A[1]	18
Data bus		24
Bus control		13
Interrupt and mode control		5
Host interface (HI08)	Port B[2]	16
Enhanced synchronous serial interface (ESSI)	Ports C and D[3]	12
Serial communication interface (SCI)	Port E[4]	3
Timer		3
OnCE/JTAG Port		6

Notes:
1. Port A signals define the external memory interface port, including the external address bus, data bus, and control signals.
2. Port B signals are the HI08 port signals multiplexed with the GPIO signals.
3. Port C and D signals are the two ESSI port signals multiplexed with the GPIO signals.
4. Port E signals are the SCI port signals multiplexed with the GPIO signals.
5. There are 5 signal connections that are not used. These are designated as no connect (NC) in the package description (see **Chapter 3**).

Note: The Clock Output (CLKOUT), BCLK, $\overline{\text{BCLK}}$, $\overline{\text{CAS}}$, and $\overline{\text{RAS[0–3]}}$ signals used by other DSP56300 family members are supported by the DSP56311 at operating frequencies up to 100 MHz. Therefore, above 100 MHz, you must enable bus arbitration by setting the Asynchronous Bus Arbitration Enable Bit (ABE) in the operating mode register. When set, the ABE bit eliminates the required set-up and hold times for $\overline{\text{BB}}$ and $\overline{\text{BG}}$ with respect to $\overline{\text{CLKOUT}}$. In addition, DRAM access is not supported above 100 MHz.



Notes:

1. The HI08 port supports a non-multiplexed or a multiplexed bus, single or double Data Strobe (DS), and single or double Host Request (HR) configurations. Since each of these modes is configured independently, any combination of these modes is possible. These HI08 signals can also be configured alternatively as GPIO signals (PB[0–15]). Signals with dual designations (for example, $\overline{\text{HAS}}$/HAS) have configurable polarity.
2. The ESSI0, ESSI1, and SCI signals are multiplexed with the Port C GPIO signals (PC[0–5]), Port D GPIO signals (PD[0–5]), and Port E GPIO signals (PE[0–2]), respectively.
3. TIO[0–2] can be configured as GPIO signals.
4. CLKOUT, BCLK, $\overline{\text{BCLK}}$, $\overline{\text{CAS}}$, and $\overline{\text{RAS}}$[0–3] are valid only for operating frequencies ≤100 MHz.

Figure 1-1. Signals Identified by Functional Group

1.6 Interrupt and Mode Control

The interrupt and mode control signals select the chip operating mode as it comes out of hardware reset. After RESET is deasserted, these inputs are hardware interrupt request lines.

Table 1-9. Interrupt and Mode Control

Signal Name	Type	State During Reset	Signal Description
MODA	Input	Schmitt-trigger Input	**Mode Select A**—MODA, MODB, MODC, and MODD select one of 16 initial chip operating modes, latched into the Operating Mode Register when the RESET signal is deasserted.
IRQA	Input		**External Interrupt Request A**—After reset, this input becomes a level-sensitive or negative-edge-triggered, maskable interrupt request input during normal instruction processing. If the processor is in the STOP or WAIT standby state and IRQA is asserted, the processor exits the STOP or WAIT state.
MODB	Input	Schmitt-trigger Input	**Mode Select B**—MODA, MODB, MODC, and MODD select one of 16 initial chip operating modes, latched into the Operating Mode Register when the RESET signal is deasserted.
IRQB	Input		**External Interrupt Request B**—After reset, this input becomes a level-sensitive or negative-edge-triggered, maskable interrupt request input during normal instruction processing. If the processor is in the WAIT standby state and IRQB is asserted, the processor exits the WAIT state.
MODC	Input	Schmitt-trigger Input	**Mode Select C**—MODA, MODB, MODC, and MODD select one of 16 initial chip operating modes, latched into the Operating Mode Register when the RESET signal is deasserted.
IRQC	Input		**External Interrupt Request C**—After reset, this input becomes a level-sensitive or negative-edge-triggered, maskable interrupt request input during normal instruction processing. If the processor is in the WAIT standby state and IRQC is asserted, the processor exits the WAIT state.
MODD	Input	Schmitt-trigger Input	**Mode Select D**—MODA, MODB, MODC, and MODD select one of 16 initial chip operating modes, latched into the Operating Mode Register when the RESET signal is deasserted.
IRQD	Input		**External Interrupt Request D**—After reset, this input becomes a level-sensitive or negative-edge-triggered, maskable interrupt request input during normal instruction processing. If the processor is in the WAIT standby state and IRQD is asserted, the processor exits the WAIT state.
RESET	Input	Schmitt-trigger Input	**Reset**—Places the chip in the Reset state and resets the internal phase generator. The Schmitt-trigger input allows a slowly rising input (such as a capacitor charging) to reset the chip reliably. When the RESET signal is deasserted, the initial chip operating mode is latched from the MODA, MODB, MODC, and MODD inputs. The RESET signal must be asserted after powerup.

Table 1-13. Enhanced Serial Synchronous Interface 1 (Continued)

Signal Name	Type	State During Reset[1,2]	Signal Description
SCK1	Input/Output	Ignored Input	**Serial Clock**—Provides the serial bit rate clock for the ESSI. The SCK1 is a clock input or output used by both the transmitter and receiver in synchronous modes or by the transmitter in asynchronous modes. Although an external serial clock can be independent of and asynchronous to the DSP system clock, it must exceed the minimum clock cycle time of 6T (that is, the system clock frequency must be at least three times the external ESSI clock frequency). The ESSI needs at least three DSP phases inside each half of the serial clock.
PD3	Input or Output		**Port D 3**—The default configuration following reset is GPIO input PD3. When configured as PD3, signal direction is controlled through the Port D Direction Register. The signal can be configured as an ESSI signal SCK1 through the Port D Control Register.
SRD1	Input	Ignored Input	**Serial Receive Data**—Receives serial data and transfers the data to the ESSI Receive Shift Register. SRD1 is an input when data is being received.
PD4	Input or Output		**Port D 4**—The default configuration following reset is GPIO input PD4. When configured as PD4, signal direction is controlled through the Port D Direction Register. The signal can be configured as an ESSI signal SRD1 through the Port D Control Register.
STD1	Output	Ignored Input	**Serial Transmit Data**—Transmits data from the Serial Transmit Shift Register. STD1 is an output when data is being transmitted.
PD5	Input or Output		**Port D 5**—The default configuration following reset is GPIO input PD5. When configured as PD5, signal direction is controlled through the Port D Direction Register. The signal can be configured as an ESSI signal STD1 through the Port D Control Register.

Notes: 1. In the Stop state, the signal maintains the last state as follows:
- If the last state is input, the signal is an ignored input.
- If the last state is output, these lines have weak keepers that maintain the last output state even if the drivers are tri-stated.

2. The Wait processing state does not affect the signal state.

1.10 Serial Communication Interface (SCI)

The SCI provides a full duplex port for serial communication with other DSPs, microprocessors, or peripherals such as modems.

Table 1-14. Serial Communication Interface

Signal Name	Type	State During Reset[1,2]	Signal Description
RXD	Input	Ignored Input	**Serial Receive Data**—Receives byte-oriented serial data and transfers it to the SCI Receive Shift Register.
PE0	Input or Output		**Port E 0**—The default configuration following reset is GPIO input PE0. When configured as PE0, signal direction is controlled through the Port E Direction Register. The signal can be configured as an SCI signal RXD through the Port E Control Register.
TXD	Output	Ignored Input	**Serial Transmit Data**—Transmits data from the SCI Transmit Data Register.
PE1	Input or Output		**Port E 1**—The default configuration following reset is GPIO input PE1. When configured as PE1, signal direction is controlled through the Port E Direction Register. The signal can be configured as an SCI signal TXD through the Port E Control Register.

Table 1-14. Serial Communication Interface (Continued)

Signal Name	Type	State During Reset[1,2]	Signal Description
SCLK	Input/Output	Ignored Input	**Serial Clock**—Provides the input or output clock used by the transmitter and/or the receiver.
PE2	Input or Output		**Port E 2**—The default configuration following reset is GPIO input PE2. When configured as PE2, signal direction is controlled through the Port E Direction Register. The signal can be configured as an SCI signal SCLK through the Port E Control Register.

Notes: 1. In the Stop state, the signal maintains the last state as follows:
- If the last state is input, the signal is an ignored input.
- If the last state is output, these lines have weak keepers that maintain the last output state even if the drivers are tri-stated.

2. The Wait processing state does not affect the signal state.

1.11 Timers

The DSP56311 has three identical and independent timers. Each timer can use internal or external clocking and can either interrupt the DSP56311 after a specified number of events (clocks) or signal an external device after counting a specific number of internal events.

Table 1-15. Triple Timer Signals

Signal Name	Type	State During Reset[1,2]	Signal Description
TIO0	Input or Output	Ignored Input	**Timer 0 Schmitt-Trigger Input/Output**— When Timer 0 functions as an external event counter or in measurement mode, TIO0 is used as input. When Timer 0 functions in watchdog, timer, or pulse modulation mode, TIO0 is used as output. The default mode after reset is GPIO input. TIO0 can be changed to output or configured as a timer I/O through the Timer 0 Control/Status Register (TCSR0).
TIO1	Input or Output	Ignored Input	**Timer 1 Schmitt-Trigger Input/Output**— When Timer 1 functions as an external event counter or in measurement mode, TIO1 is used as input. When Timer 1 functions in watchdog, timer, or pulse modulation mode, TIO1 is used as output. The default mode after reset is GPIO input. TIO1 can be changed to output or configured as a timer I/O through the Timer 1 Control/Status Register (TCSR1).
TIO2	Input or Output	Ignored Input	**Timer 2 Schmitt-Trigger Input/Output**— When Timer 2 functions as an external event counter or in measurement mode, TIO2 is used as input. When Timer 2 functions in watchdog, timer, or pulse modulation mode, TIO2 is used as output. The default mode after reset is GPIO input. TIO2 can be changed to output or configured as a timer I/O through the Timer 2 Control/Status Register (TCSR2).

Notes: 1. In the Stop state, the signal maintains the last state as follows:
- If the last state is input, the signal is an ignored input.
- If the last state is output, these lines have weak keepers that maintain the last output state even if the drivers are tri-stated.

2. The Wait processing state does not affect the signal state.

2.4 AC Electrical Characteristics

The timing waveforms shown in the AC electrical characteristics section are tested with a V_{IL} maximum of 0.3 V and a V_{IH} minimum of 2.4 V for all pins except EXTAL, which is tested using the input levels shown in Note 6 of **Table 2-2**. AC timing specifications, which are referenced to a device input signal, are measured in production with respect to the 50 percent point of the respective input signal's transition. DSP56311 output levels are measured with the production test machine V_{OL} and V_{OH} reference levels set at 0.4 V and 2.4 V, respectively.

Note: Although the minimum value for the frequency of EXTAL is 0 MHz, the device AC test conditions are 15 MHz and rated speed.

2.4.1 Internal Clocks

Table 2-4. Internal Clocks

Characteristics	Symbol	Expression		
		Min	Typ	Max
Internal operation frequency with PLL enabled	f	—	(Ef × MF)/ (PDF × DF)	—
Internal operation frequency with PLL disabled	f	—	Ef/2	—
Internal clock high period • With PLL disabled • With PLL enabled and MF ≤4 • With PLL enabled and MF > 4	T_H	— 0.49 × ET_C × PDF × DF/MF 0.47 × ET_C × PDF × DF/MF	ET_C — —	— 0.51 × ET_C × PDF × DF/MF 0.53 × ET_C × PDF × DF/MF
Internal clock low period • With PLL disabled • With PLL enabled and MF ≤4 • With PLL enabled and MF > 4	T_L	— 0.49 × ET_C × PDF × DF/MF 0.47 × ET_C × PDF × DF/MF	ET_C — —	— 0.51 × ET_C × PDF × DF/MF 0.53 × ET_C × PDF × DF/MF
Internal clock cycle time with PLL enabled	T_C	—	ET_C × PDF × DF/MF	—
Internal clock cycle time with PLL disabled	T_C	—	2 × ET_C	—
Instruction cycle time	I_{CYC}	—	T_C	—

Notes: 1. DF = Division Factor; Ef = External frequency; ET_C = External clock cycle; MF = Multiplication Factor; PDF = Predivision Factor; T_C = internal clock cycle.
2. See the PLL and Clock Generation section in the *DSP56300 Family Manual* for a details on the PLL.

Table 2-7. Reset, Stop, Mode Select, and Interrupt Timing[6] (Continued)

No.	Characteristics	Expression	150 MHz		Unit
			Min	Max	
26	Duration of level sensitive $\overline{\text{IRQA}}$ assertion to ensure interrupt service (when exiting Stop)[2, 3]				
	• PLL is not active during Stop (PCTL Bit 17 = 0) and Stop delay is enabled (Operating Mode Register Bit 6 = 0)	Minimum: $PLC \times ET_C \times PDF + (128K - PLC/2) \times T_C$	13.6	—	ms
	• PLL is not active during Stop (PCTL Bit 17 = 0) and Stop delay is not enabled (Operating Mode Register Bit 6 = 1)	$PLC \times ET_C \times PDF + (20.5 \pm 0.5) \times T_C$	12.3	—	ms
	• PLL is active during Stop (PCTL Bit 17 = 1) (implies no Stop delay)	$5.5 \times T_C$	36.7	—	ns
27	Interrupt Request Rate	Maximum:			
	• HI08, ESSI, SCI, Timer	$12 \times T_C$	—	80.0	ns
	• DMA	$8 \times T_C$	—	53.3	ns
	• $\overline{\text{IRQ}}$, $\overline{\text{NMI}}$ (edge trigger)	$8 \times T_C$	—	53.3	ns
	• $\overline{\text{IRQ}}$, $\overline{\text{NMI}}$ (level trigger)	$12 \times T_C$	—	80.0	ns
28	DMA Request Rate	Maximum:			
	• Data read from HI08, ESSI, SCI	$6 \times T_C$	—	40.0	ns
	• Data write to HI08, ESSI, SCI	$7 \times T_C$	—	46.7	ns
	• Timer	$2 \times T_C$	—	13.3	ns
	• $\overline{\text{IRQ}}$, $\overline{\text{NMI}}$ (edge trigger)	$3 \times T_C$	—	20.0	ns
29	Delay from $\overline{\text{IRQA}}$, $\overline{\text{IRQB}}$, $\overline{\text{IRQC}}$, $\overline{\text{IRQD}}$, $\overline{\text{NMI}}$ assertion to external memory (DMA source) access address out valid	Minimum: $4.25 \times T_C + 2.0$	30.3	—	ns

Notes:

1. When fast interrupts are used and $\overline{\text{IRQA}}$, $\overline{\text{IRQB}}$, $\overline{\text{IRQC}}$, and $\overline{\text{IRQD}}$ are defined as level-sensitive, timings 19 through 21 apply to prevent multiple interrupt service. To avoid these timing restrictions, the deasserted Edge-triggered mode is recommended when fast interrupts are used. Long interrupts are recommended for Level-sensitive mode.
2. This timing depends on several settings:
   • For PLL disable, using internal oscillator (PLL Control Register (PCTL) Bit 16 = 0) and oscillator disabled during Stop (PCTL Bit 17 = 0), a stabilization delay is required to assure that the oscillator is stable before programs are executed. Resetting the Stop delay (Operating Mode Register Bit 6 = 0) provides the proper delay. While Operating Mode Register Bit 6 = 1 can be set, it is not recommended, and these specifications do not guarantee timings for that case.
   • For PLL disable, using internal oscillator (PCTL Bit 16 = 0) and oscillator enabled during Stop (PCTL Bit 17=1), no stabilization delay is required and recovery is minimal (Operating Mode Register Bit 6 setting is ignored).
   • For PLL disable, using external clock (PCTL Bit 16 = 1), no stabilization delay is required and recovery time is defined by the PCTL Bit 17 and Operating Mode Register Bit 6 settings.
   • For PLL enable, if PCTL Bit 17 is 0, the PLL is shutdown during Stop. Recovering from Stop requires the PLL to get locked. The PLL lock procedure duration, PLL Lock Cycles (PLC), may be in the range of 0 to 1000 cycles. This procedure occurs in parallel with the stop delay counter, and stop recovery ends when the last of these two events occurs. The stop delay counter completes count or PLL lock procedure completion.
   • PLC value for PLL disable is 0.
   • The maximum value for ET_C is 4096 (maximum MF) divided by the desired internal frequency (that is, for 66 MHz it is 4096/66 MHz = 62 µs). During the stabilization period, T_C, T_H, and T_L is not constant, and their width may vary, so timing may vary as well.
3. Periodically sampled and not 100 percent tested.
4. Value depends on clock source:
   • For an external clock generator, $\overline{\text{RESET}}$ duration is measured while $\overline{\text{RESET}}$ is asserted, V_{CC} is valid, and the EXTAL input is active and valid.
   • For an internal oscillator, $\overline{\text{RESET}}$ duration is measured while $\overline{\text{RESET}}$ is asserted and V_{CC} is valid. The specified timing reflects the crystal oscillator stabilization time after power-up. This number is affected both by the specifications of the crystal and other components connected to the oscillator and reflects worst case conditions.
   • When the V_{CC} is valid, but the other "required $\overline{\text{RESET}}$ duration" conditions (as specified above) have not been yet met, the device circuitry is in an uninitialized state that can result in significant power consumption and heat-up. Designs should minimize this state to the shortest possible duration.
5. If PLL does not lose lock.
6. V_{CCQH} = 3.3 V ±0.3 V, V_{CC} = 1.8 V ±0.1 V; T_J = –40°C to +100°C, C_L = 50 pF.
7. WS = number of wait states (measured in clock cycles, number of T_C).
8. Use expression to compute maximum value.

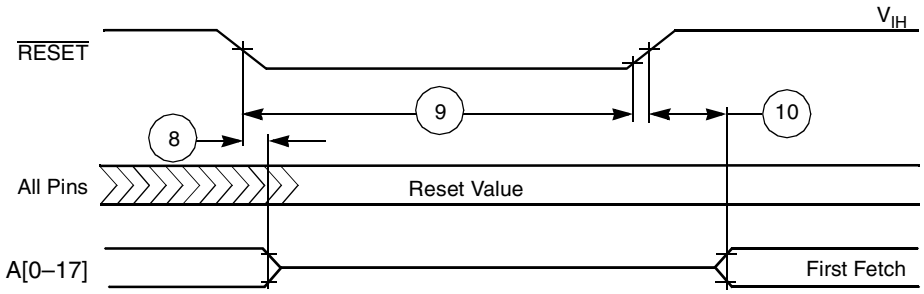
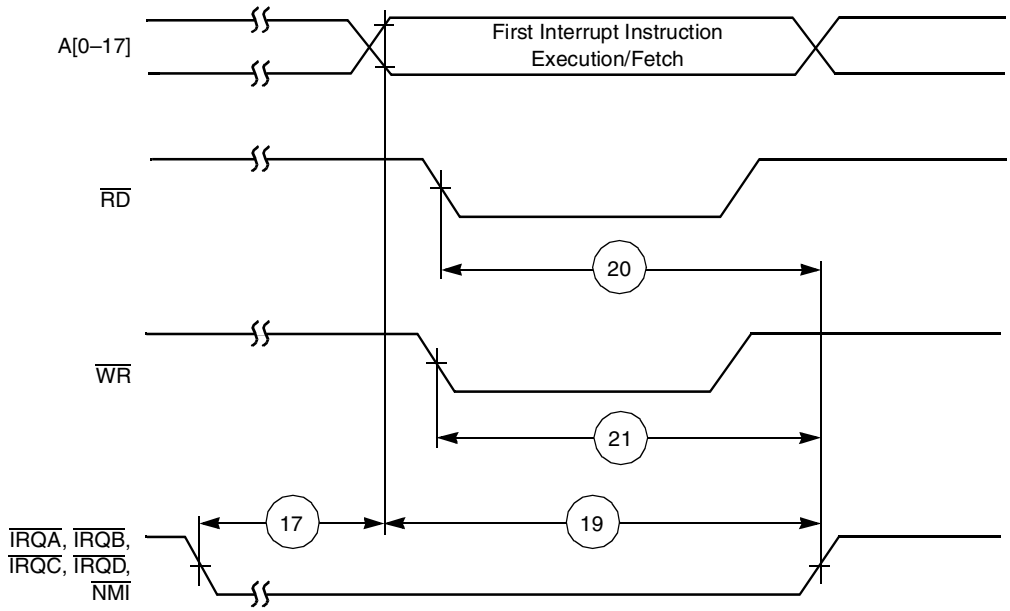
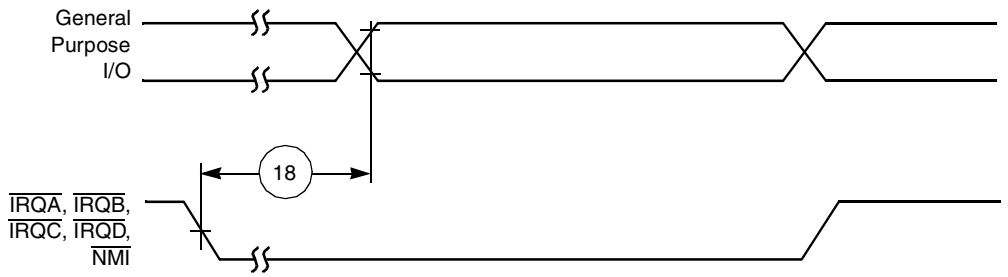


Figure 2-3. Reset Timing



a) First Interrupt Instruction Execution



b) General-Purpose I/O

Figure 2-4. External Fast Interrupt Timing

Table 2-9. DRAM Page Mode Timings, Three Wait States[1,2,3] (Continued)

No.	Characteristics	Symbol	Expression[4]	100 MHz		Unit
				Min	Max	
134	$\overline{CAS}$ deassertion to data not valid (read hold time)	t_{OFF}		0.0	—	ns
135	Last $\overline{CAS}$ assertion to $\overline{RAS}$ deassertion	t_{RSH}	$2.5 \times T_C - 4.0$	21.0	—	ns
136	Previous $\overline{CAS}$ deassertion to $\overline{RAS}$ deassertion	t_{RHCP}	$4.5 \times T_C - 4.0$	41.0	—	ns
137	$\overline{CAS}$ assertion pulse width	t_{CAS}	$2 \times T_C - 4.0$	16.0	—	ns
138	Last $\overline{CAS}$ deassertion to $\overline{RAS}$ assertion[5] • BRW[1–0] = 00, 01—not applicable • BRW[1–0] = 10 • BRW[1–0] = 11	t_{CRP}	 — $4.75 \times T_C - 6.0$ $6.75 \times T_C - 6.0$	 — 41.5 61.5	 — — —	 — ns ns
139	$\overline{CAS}$ deassertion pulse width	t_{CP}	$1.5 \times T_C - 4.0$	11.0	—	ns
140	Column address valid to $\overline{CAS}$ assertion	t_{ASC}	$T_C - 4.0$	6.0	—	ns
141	$\overline{CAS}$ assertion to column address not valid	t_{CAH}	$2.5 \times T_C - 4.0$	21.0	—	ns
142	Last column address valid to $\overline{RAS}$ deassertion	t_{RAL}	$4 \times T_C - 4.0$	36.0	—	ns
143	$\overline{WR}$ deassertion to $\overline{CAS}$ assertion	t_{RCS}	$1.25 \times T_C - 4.0$	8.5	—	ns
144	$\overline{CAS}$ deassertion to $\overline{WR}$ assertion	t_{RCH}	$0.75 \times T_C - 4.0$	3.5	—	ns
145	$\overline{CAS}$ assertion to $\overline{WR}$ deassertion	t_{WCH}	$2.25 \times T_C - 4.2$	18.3	—	ns
146	$\overline{WR}$ assertion pulse width	t_{WP}	$3.5 \times T_C - 4.5$	30.5	—	ns
147	Last $\overline{WR}$ assertion to $\overline{RAS}$ deassertion	t_{RWL}	$3.75 \times T_C - 4.3$	33.2	—	ns
148	$\overline{WR}$ assertion to $\overline{CAS}$ deassertion	t_{CWL}	$3.25 \times T_C - 4.3$	28.2	—	ns
149	Data valid to $\overline{CAS}$ assertion (write)	t_{DS}	$0.5 \times T_C - 4.5$	0.5	—	ns
150	$\overline{CAS}$ assertion to data not valid (write)	t_{DH}	$2.5 \times T_C - 4.0$	21.0	—	ns
151	$\overline{WR}$ assertion to $\overline{CAS}$ assertion	t_{WCS}	$1.25 \times T_C - 4.3$	8.2	—	ns
152	Last $\overline{RD}$ assertion to $\overline{RAS}$ deassertion	t_{ROH}	$3.5 \times T_C - 4.0$	31.0	—	ns
153	$\overline{RD}$ assertion to data valid	t_{GA}	$2.5 \times T_C - 5.7$	—	19.3	ns
154	$\overline{RD}$ deassertion to data not valid[6]	t_{GZ}		0.0	—	ns
155	$\overline{WR}$ assertion to data active		$0.75 \times T_C - 1.5$	6.0	—	ns
156	$\overline{WR}$ deassertion to data high impedance		$0.25 \times T_C$	—	2.5	ns

Notes:
1. The number of wait states for Page mode access is specified in the DRAM Control Register.
2. The refresh period is specified in the DRAM Control Register.
3. The asynchronous delays specified in the expressions are valid for the DSP56311.
4. All the timings are calculated for the worst case. Some of the timings are better for specific cases (for example, t_{PC} equals $4 \times T_C$ for read-after-read or write-after-write sequences). An expression is used to compute the number listed as the minimum or maximum value listed, as appropriate.
5. BRW[1–0] (DRAM control register bits) defines the number of wait states that should be inserted in each DRAM out-of page-access.
6. $\overline{RD}$ deassertion always occurs after $\overline{CAS}$ deassertion; therefore, the restricted timing is t_{OFF} and not t_{GZ}.

Table 2-10. DRAM Page Mode Timings, Four Wait States[1,2,3]

No.	Characteristics	Symbol	Expression[4]	100 MHz		Unit
				Min	Max	
131	Page mode cycle time for two consecutive accesses of the same direction Page mode cycle time for mixed (read and write) accesses	 t_{PC}	$5 \times T_C$ $4.5 \times T_C$	50.0 45.0	— —	ns ns
132	$\overline{CAS}$ assertion to data valid (read)	t_{CAC}	$2.75 \times T_C - 5.7$	—	21.8	ns
133	Column address valid to data valid (read)	t_{AA}	$3.75 \times T_C - 5.7$	—	31.8	ns
134	$\overline{CAS}$ deassertion to data not valid (read hold time)	t_{OFF}		0.0	—	ns
135	Last $\overline{CAS}$ assertion to $\overline{RAS}$ deassertion	t_{RSH}	$3.5 \times T_C - 4.0$	31.0	—	ns
136	Previous $\overline{CAS}$ deassertion to $\overline{RAS}$ deassertion	t_{RHCP}	$6 \times T_C - 4.0$	56.0	—	ns
137	$\overline{CAS}$ assertion pulse width	t_{CAS}	$2.5 \times T_C - 4.0$	21.0	—	ns
138	Last $\overline{CAS}$ deassertion to $\overline{RAS}$ assertion[5] • BRW[1–0] = 00, 01—Not applicable • BRW[1–0] = 10 • BRW[1–0] = 11	t_{CRP}	 — $5.25 \times T_C - 6.0$ $7.25 \times T_C - 6.0$	 — 46.5 66.5	 — — —	 — ns ns
139	$\overline{CAS}$ deassertion pulse width	t_{CP}	$2 \times T_C - 4.0$	16.0	—	ns
140	Column address valid to $\overline{CAS}$ assertion	t_{ASC}	$T_C - 4.0$	6.0	—	ns
141	$\overline{CAS}$ assertion to column address not valid	t_{CAH}	$3.5 \times T_C - 4.0$	31.0	—	ns
142	Last column address valid to $\overline{RAS}$ deassertion	t_{RAL}	$5 \times T_C - 4.0$	46.0	—	ns
143	$\overline{WR}$ deassertion to $\overline{CAS}$ assertion	t_{RCS}	$1.25 \times T_C - 4.0$	8.5	—	ns
144	$\overline{CAS}$ deassertion to $\overline{WR}$ assertion	t_{RCH}	$1.25 \times T_C - 3.7$	8.8	—	ns
145	$\overline{CAS}$ assertion to $\overline{WR}$ deassertion	t_{WCH}	$3.25 \times T_C - 4.2$	28.3	—	ns
146	$\overline{WR}$ assertion pulse width	t_{WP}	$4.5 \times T_C - 4.5$	40.5	—	ns
147	Last $\overline{WR}$ assertion to $\overline{RAS}$ deassertion	t_{RWL}	$4.75 \times T_C - 4.3$	43.2	—	ns
148	$\overline{WR}$ assertion to $\overline{CAS}$ deassertion	t_{CWL}	$3.75 \times T_C - 4.3$	33.2	—	ns
149	Data valid to $\overline{CAS}$ assertion (write)	t_{DS}	$0.5 \times T_C - 4.5$	0.5	—	ns
150	$\overline{CAS}$ assertion to data not valid (write)	t_{DH}	$3.5 \times T_C - 4.0$	31.0	—	ns
151	$\overline{WR}$ assertion to $\overline{CAS}$ assertion	t_{WCS}	$1.25 \times T_C - 4.3$	8.2	—	ns
152	Last $\overline{RD}$ assertion to $\overline{RAS}$ deassertion	t_{ROH}	$4.5 \times T_C - 4.0$	41.0	—	ns
153	$\overline{RD}$ assertion to data valid	t_{GA}	$3.25 \times T_C - 5.7$	—	26.8	ns
154	$\overline{RD}$ deassertion to data not valid[6]	t_{GZ}		0.0	—	ns
155	$\overline{WR}$ assertion to data active		$0.75 \times T_C - 1.5$	6.0	—	ns
156	$\overline{WR}$ deassertion to data high impedance		$0.25 \times T_C$	—	2.5	ns

Notes:
1. The number of wait states for Page mode access is specified in the DRAM Control Register.
2. The refresh period is specified in the DRAM Control Register.
3. The asynchronous delays specified in the expressions are valid for the DSP56311.
4. All the timings are calculated for the worst case. Some of the timings are better for specific cases (for example, t_{PC} equals $3 \times T_C$ for read-after-read or write-after-write sequences). An expressions is used to calculate the maximum or minimum value listed, as appropriate.
5. BRW[1–0] (DRAM control register bits) defines the number of wait states that should be inserted in each DRAM out-of-page access.
6. $\overline{RD}$ deassertion always occurs after $\overline{CAS}$ deassertion; therefore, the restricted timing is t_{OFF} and not t_{GZ}.

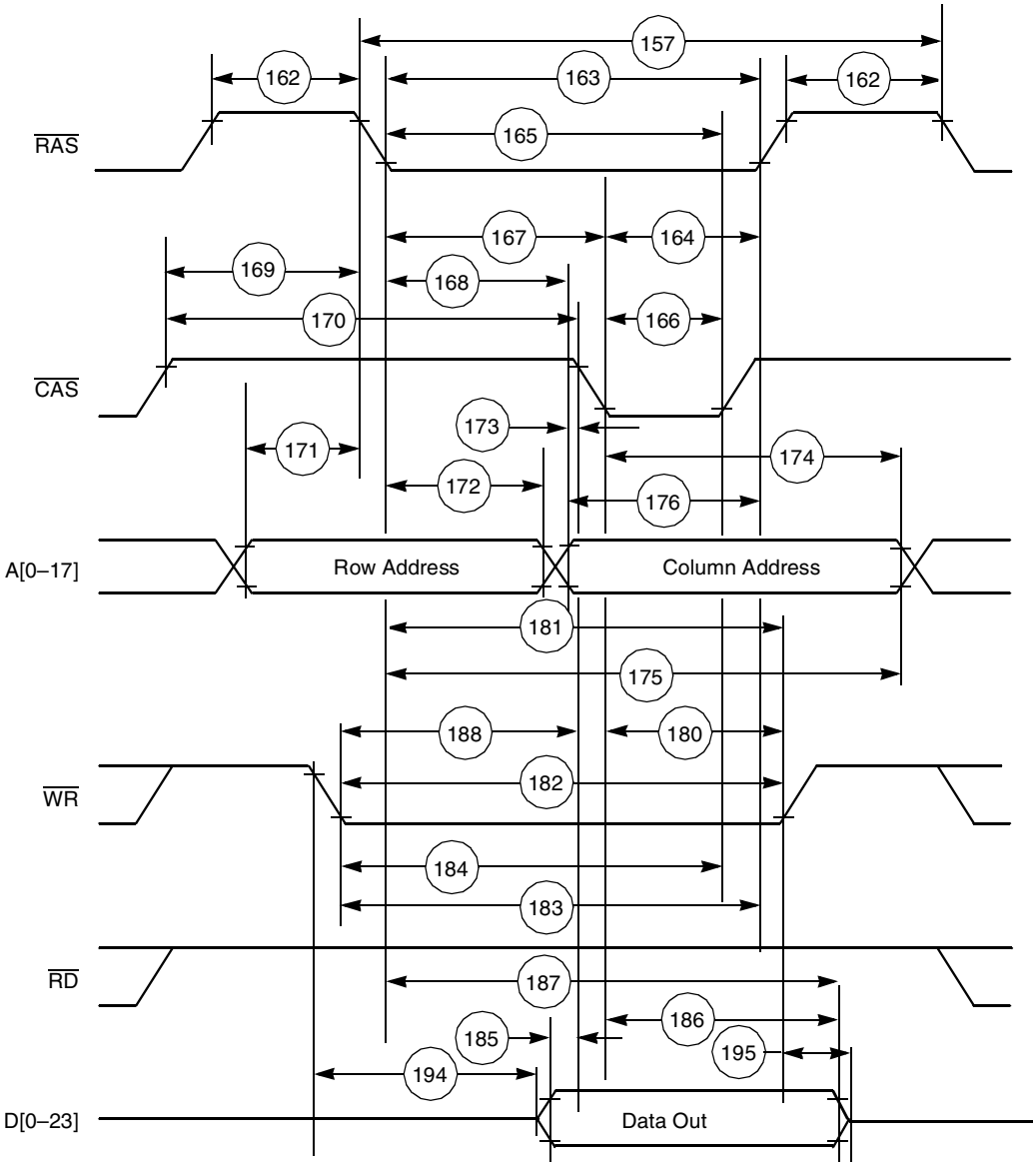


Figure 2-17. DRAM Out-of-Page Write Access

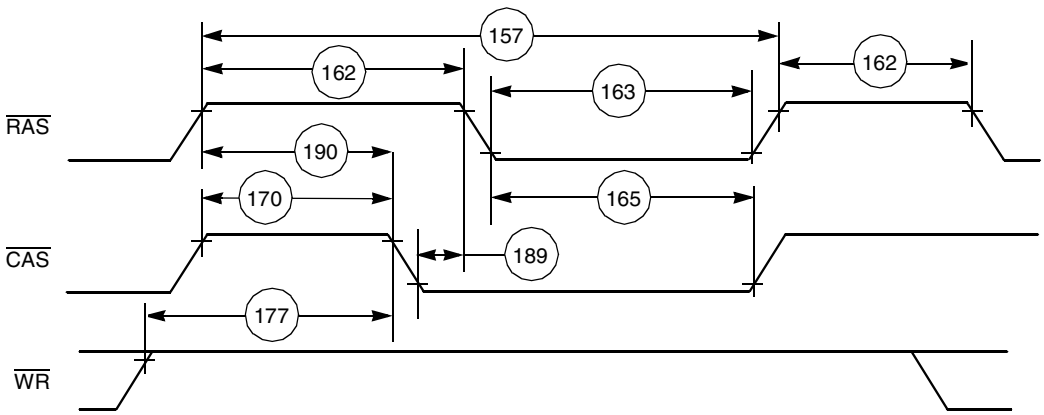


Figure 2-18. DRAM Refresh Access

Table 2-16. ESSI Timings (Continued)

No.	Characteristics[4, 6]	Symbol	Expression	150 MHz		Cond-ition[5]	Unit
				Min	Max		
451	TXC rising edge to FST out (word-length) low			— —	31.0 17.0	x ck i ck	ns
452	TXC rising edge to data out enable from high impedance			— —	31.0 17.0	x ck i ck	ns
453	TXC rising edge to transmitter 0 drive enable assertion			— —	34.0 20.0	x ck i ck	ns
454	TXC rising edge to data out valid		$35 + 0.5 \times T_C$	— —	38.4 21.0	x ck i ck	ns
455	TXC rising edge to data out high impedance[3]			— —	31.0 16.0	x ck i ck	ns
456	TXC rising edge to transmitter 0 drive enable deassertion[3]			— —	34.0 20.0	x ck i ck	ns
457	FST input (bl, wr)[6] set-up time before TXC falling edge[2]			2.0 21.0	— —	x ck i ck	ns
458	FST input (wl)[6] to data out enable from high impedance			—	27.0	—	ns
459	FST input (wl) to transmitter 0 drive enable assertion			—	31.0	—	ns
460	FST input (wl)[6] set-up time before TXC falling edge			2.5 21.0	— —	x ck i ck	ns
461	FST input hold time after TXC falling edge			4.0 0.0	— —	x ck i ck	ns
462	Flag output valid after TXC rising edge			— —	32.0 18.0	x ck i ck	ns

Notes:
1. For the internal clock, the external clock cycle is defined by the instruction cycle time (timing 7 in **Table 2-5** on page 2-6) and the ESSI Control Register.
2. The word-length-relative frame sync signal waveform operates the same way as the bit-length frame sync signal waveform, but spreads from one serial clock before the first bit clock (same as the Bit Length Frame Sync signal) until the one before last bit clock of the first word in the frame.
3. Periodically sampled and not 100 percent tested
4. V_{CCQH} = 3.3 V ± 0.3 V, V_{CC} = 1.8 V ± 0.1 V; T_J = –40°C to +100 °C, C_L = 50 pF.
5. TXC (SCK Pin) = transmit clock
   RXC (SC0 or SCK pin) = receive clock
   FST (SC2 pin) = transmit frame sync
   FSR (SC1 or SC2 pin) receive frame sync
6. i ck = Internal Clock; x ck = external clock
   i ck a = internal clock, Asynchronous mode (asynchronous implies that TXC and RXC are two different clocks)
   i ck s = internal clock, Synchronous mode (synchronous implies that TXC and RXC are the same clock)
   bl = bit length
   wl = word length
   wr = word length relative

3.1 Package Description

Top and bottom views of the MAP-BGA packages are shown in **Figure 3-1** and **Figure 3-2** with their pin-outs.

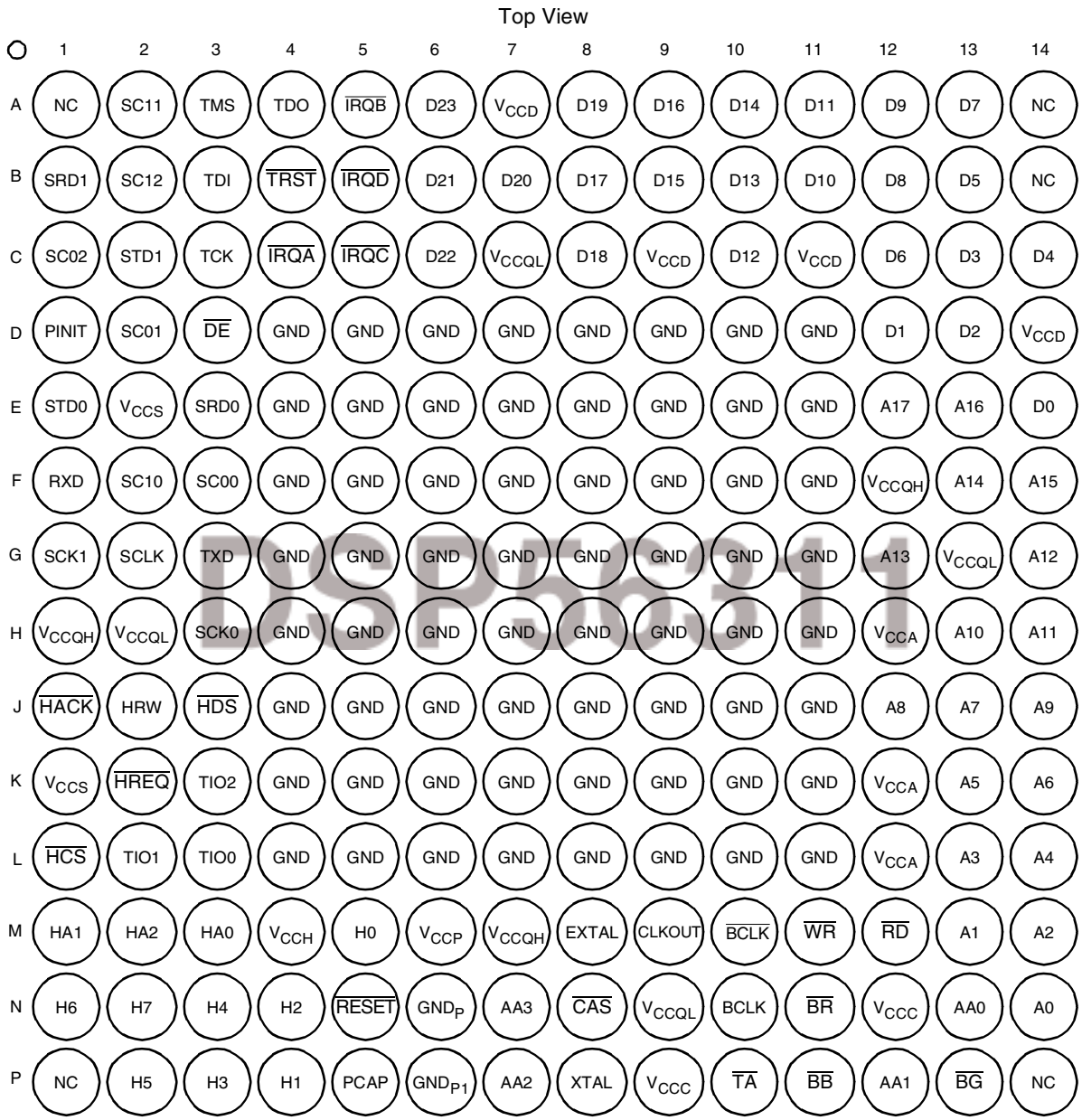


Figure 3-1. DSP56311 MAP-BGA Package, Top View

Design Considerations 4

This section describes various areas to consider when incorporating the DSP56311 device into a system design.

4.1 Thermal Design Considerations

An estimate of the chip junction temperature, T_J, in °C can be obtained from this equation:

Equation 1: $$T_J = T_A + (P_D \times R_{\theta JA})$$

Where:

T_A	=	ambient temperature °C
$R_{\theta JA}$	=	package junction-to-ambient thermal resistance °C/W
P_D	=	power dissipation in package

Historically, thermal resistance has been expressed as the sum of a junction-to-case thermal resistance and a case-to-ambient thermal resistance, as in this equation:

Equation 2: $$R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$$

Where:

$R_{\theta JA}$	=	package junction-to-ambient thermal resistance °C/W
$R_{\theta JC}$	=	package junction-to-case thermal resistance °C/W
$R_{\theta CA}$	=	package case-to-ambient thermal resistance °C/W

$R_{\theta JC}$ is device-related and cannot be influenced by the user. The user controls the thermal environment to change the case-to-ambient thermal resistance, $R_{\theta CA}$. For example, the user can change the air flow around the device, add a heat sink, change the mounting arrangement on the printed circuit board (PCB) or otherwise change the thermal dissipation capability of the area surrounding the device on a PCB. This model is most useful for ceramic packages with heat sinks; some 90 percent of the heat flow is dissipated through the case to the heat sink and out to the ambient environment. For ceramic packages, in situations where the heat flow is split between a path to the case and an alternate path through the PCB, analysis of the device thermal performance may need the additional modeling capability of a system-level thermal simulation tool.

The thermal performance of plastic packages is more dependent on the temperature of the PCB to which the package is mounted. Again, if the estimates obtained from $R_{\theta JA}$ do not satisfactorily answer whether the thermal performance is adequate, a system-level model may be appropriate.

A complicating factor is the existence of three common ways to determine the junction-to-case thermal resistance in plastic packages.

- To minimize temperature variation across the surface, the thermal resistance is measured from the junction to the outside surface of the package (case) closest to the chip mounting area when that surface has a proper heat sink.
- To define a value approximately equal to a junction-to-board thermal resistance, the thermal resistance is measured from the junction to the point at which the leads attach to the case.
- If the temperature of the package case (T_T) is determined by a thermocouple, thermal resistance is computed from the value obtained by the equation $(T_J - T_T)/P_D$.

As noted earlier, the junction-to-case thermal resistances quoted in this data sheet are determined using the first definition. From a practical standpoint, that value is also suitable to determine the junction temperature from a case thermocouple reading in forced convection environments. In natural convection, the use of the junction-to-case thermal resistance to estimate junction temperature from a thermocouple reading on the case of the package will yield an estimate of a junction temperature slightly higher than actual temperature. Hence, the new thermal metric, thermal characterization parameter or Ψ_{JT}, has been defined to be $(T_J - T_T)/P_D$. This value gives a better estimate of the junction temperature in natural convection when the surface temperature of the package is used. Remember that surface temperature readings of packages are subject to significant errors caused by inadequate attachment of the sensor to the surface and to errors caused by heat loss to the sensor. The recommended technique is to attach a 40-gauge thermocouple wire and bead to the top center of the package with thermally conductive epoxy.

4.2 Electrical Design Considerations

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for example, either GND or V_{CC}).

Use the following list of recommendations to ensure correct DSP operation.

- Provide a low-impedance path from the board power supply to each V_{CC} pin on the DSP and from the board ground to each GND pin.
- Use at least four 0.01–0.1 µF bypass capacitors for the core and PLL power and six 0.01–0.1 µF bypass capacitors for I/O power positioned as closely as possible to the four sides of the package to connect the V_{CC} power source to GND.
- Ensure that capacitor leads and associated printed circuit traces that connect to the chip V_{CC} and GND pins are less than 0.5 inch per capacitor lead.
- Use at least a four-layer PCB with two inner layers for V_{CC} and GND.

- Because the DSP output signals have fast rise and fall times, PCB trace lengths should be minimal. This recommendation particularly applies to the address and data buses as well as the $\overline{\text{IRQA}}$, $\overline{\text{IRQB}}$, $\overline{\text{IRQC}}$, $\overline{\text{IRQD}}$, $\overline{\text{TA}}$, and $\overline{\text{BG}}$ pins. Maximum PCB trace lengths on the order of 6 inches are recommended.
- Consider all device loads as well as parasitic capacitance due to PCB traces when you calculate capacitance. This is especially critical in systems with higher capacitive loads that could create higher transient currents in the V_{CC} and GND circuits.
- All inputs must be terminated (that is, not allowed to float) by CMOS levels except for the three pins with internal pull-up resistors ($\overline{\text{TRST}}$, TMS, $\overline{\text{DE}}$).
- Take special care to minimize noise levels on the V_{CCP}, GND_P, and GND_{P1} pins.
- The following pins must be asserted during power-up: $\overline{\text{RESET}}$ and $\overline{\text{TRST}}$. A stable EXTAL signal should be supplied before deassertion of $\overline{\text{RESET}}$. If the V_{CC} reaches the required level before EXTAL is stable or other "required $\overline{\text{RESET}}$ duration" conditions are met (see **Table 2-7**), the device circuitry can be in an uninitialized state that may result in significant power consumption and heat-up. Designs should minimize this condition to the shortest possible duration.
- Ensure that during power-up, and throughout the DSP56311 operation, V_{CCQH} is always higher or equal to the V_{CC} voltage level.
- If multiple DSP devices are on the same board, check for cross-talk or excessive spikes on the supplies due to synchronous operation of the devices.
- The Port A data bus (D[0–23]), HI08, ESSI0, ESSI1, SCI, and timers all use internal keepers to maintain the last output value even when the internal signal is tri-stated. Typically, no pull-up or pull-down resistors should be used with these signal lines. However, if the DSP is connected to a device that requires pull-up resistors (such as an MPC8260), the recommended resistor value is 10 KΩ or less. If more than one DSP must be connected in parallel to the other device, the pull-up resistor value requirement changes as follows:
  - 2 DSPs = 7 KΩ or less
  - 3 DSPs = 4 KΩ or less
  - 4 DSPs = 3 KΩ or less
  - 5 DSPs = 2 KΩ or less
  - 6 DSPs = 1.5 KΩ or less

4.3 Power Consumption Considerations

Power dissipation is a key issue in portable DSP applications. Some of the factors affecting current consumption are described in this section. Most of the current consumed by CMOS devices is alternating current (ac), which is charging and discharging the capacitances of the pins and internal nodes. Current consumption is described by this formula:

Equation 3: $I = C \times V \times f$

Where:

C	=	node/pin capacitance
V	=	voltage swing
f	=	frequency of node/pin toggle

Example 4-1. Current Consumption

For a Port A address pin loaded with 50 pF capacitance, operating at 3.3 V, with a 66 MHz clock, toggling at its maximum possible rate (33 MHz), the current consumption is expressed in **Equation 4**.

Equation 4: $I = 50 \times 10^{-12} \times 3.3 \times 33 \times 10^{6} = 5.48\ mA$

The maximum internal current (I_{CCI}max) value reflects the typical possible switching of the internal buses on best-case operation conditions—not necessarily a real application case. The typical internal current (I_{CCItyp}) value reflects the average switching of the internal buses on typical operating conditions. Perform the following steps for applications that require very low current consumption:

1. Set the EBD bit when you are not accessing external memory.
2. Minimize external memory accesses, and use internal memory accesses.
3. Minimize the number of pins that are switching.
4. Minimize the capacitive load on the pins.
5. Connect the unused inputs to pull-up or pull-down resistors.
6. Disable unused peripherals.
7. Disable unused pin activity (for example, CLKOUT, XTAL).

One way to evaluate power consumption is to use a current-per-MIPS measurement methodology to minimize specific board effects (that is, to compensate for measured board current not caused by the DSP). A benchmark power consumption test algorithm is listed in **Appendix A**. Use the test algorithm, specific test current measurements, and the following equation to derive the current-per-MIPS value.

Equation 5: $\text{MIPS} = I / \text{MHz} = (I_{typF2} - I_{typF1}) / (F2 - F1)$

Where:

I_{typF2}	=	current at F2
I_{typF1}	=	current at F1
F2	=	high frequency (any specified operating frequency)
F1	=	low frequency (any specified operating frequency lower than F2)

Note: F1 should be significantly less than F2. For example, F2 could be 66 MHz and F1 could be 33 MHz. The degree of difference between F1 and F2 determines the amount of precision with which the current rating can be determined for an application.

4.4 PLL Performance Issues

The following explanations should be considered as general observations on expected PLL behavior. There is no test that replicates these exact numbers. These observations were measured on a limited number of parts and were not verified over the entire temperature and voltage ranges.

4.4.1 Phase Skew Performance

The phase skew of the PLL is defined as the time difference between the falling edges of EXTAL and CLKOUT for a given capacitive load on CLKOUT, over the entire process, temperature and voltage ranges. As defined in **Figure 2-2**, *External Clock Timing*, on page 2-5 for input frequencies greater than 15 MHz and the MF ≤4, this skew is greater than or equal to 0.0 ns and less than 1.8 ns; otherwise, this skew is not guaranteed. However, for MF < 10 and input frequencies greater than 10 MHz, this skew is between −1.4 ns and +3.2 ns.

4.4.2 Phase Jitter Performance

The phase jitter of the PLL is defined as the variations in the skew between the falling edges of EXTAL and CLKOUT for a given device in specific temperature, voltage, input frequency, MF, and capacitive load on CLKOUT. These variations are a result of the PLL locking mechanism. For input frequencies greater than 15 MHz and MF ≤4, this jitter is less than ±0.6 ns; otherwise, this jitter is not guaranteed. However, for MF < 10 and input frequencies greater than 10 MHz, this jitter is less than ±2 ns.

```
M_DOR2 EQU $FFFFF1                  ; DMA Offset Register 2
M_DOR3 EQU $FFFFF0                  ; DMA Offset Register 3


;       Register Addresses Of DMA0

M_DSR0 EQU $FFFFEF                  ; DMA0 Source Address Register
M_DDR0 EQU $FFFFEE                  ; DMA0 Destination Address Register
M_DCO0 EQU $FFFFED                  ; DMA0 Counter
M_DCR0 EQU $FFFFEC                  ; DMA0 Control Register

;       Register Addresses Of DMA1

M_DSR1 EQU $FFFFEB                  ; DMA1 Source Address Register
M_DDR1 EQU $FFFFEA                  ; DMA1 Destination Address Register
M_DCO1 EQU $FFFFE9                  ; DMA1 Counter
M_DCR1 EQU $FFFFE8                  ; DMA1 Control Register

;       Register Addresses Of DMA2

M_DSR2 EQU $FFFFE7                  ; DMA2 Source Address Register
M_DDR2 EQU $FFFFE6                  ; DMA2 Destination Address Register
M_DCO2 EQU $FFFFE5                  ; DMA2 Counter
M_DCR2 EQU $FFFFE4                  ; DMA2 Control Register

;       Register Addresses Of DMA4

M_DSR3 EQU $FFFFE3                  ; DMA3 Source Address Register
M_DDR3 EQU $FFFFE2                  ; DMA3 Destination Address Register
M_DCO3 EQU $FFFFE1                  ; DMA3 Counter
M_DCR3 EQU $FFFFE0                  ; DMA3 Control Register

;       Register Addresses Of DMA4


M_DSR4 EQU $FFFFDF                  ; DMA4 Source Address Register
M_DDR4 EQU $FFFFDE                  ; DMA4 Destination Address Register
M_DCO4 EQU $FFFFDD                  ; DMA4 Counter
M_DCR4 EQU $FFFFDC                  ; DMA4 Control Register

;       Register Addresses Of DMA5

M_DSR5 EQU $FFFFDB                  ; DMA5 Source Address Register
M_DDR5 EQU $FFFFDA                  ; DMA5 Destination Address Register
M_DCO5 EQU $FFFFD9                  ; DMA5 Counter
M_DCR5 EQU $FFFFD8                  ; DMA5 Control Register

;      DMA Control Register

M_DSS EQU $3                        ; DMA Source Space Mask (DSS0-Dss1)
M_DSS0 EQU 0                        ; DMA Source Memory space 0
M_DSS1 EQU 1                        ; DMA Source Memory space 1
M_DDS EQU $C                        ; DMA Destination Space Mask (DDS-DDS1)
M_DDS0 EQU 2                        ; DMA Destination Memory Space 0
M_DDS1 EQU 3                        ; DMA Destination Memory Space 1
M_DAM EQU $3f0                      ; DMA Address Mode Mask (DAM5-DAM0)
M_DAM0  EQU 4                       ; DMA Address Mode 0
M_DAM1  EQU 5                       ; DMA Address Mode 1
M_DAM2  EQU 6                       ; DMA Address Mode 2
M_DAM3  EQU 7                       ; DMA Address Mode 3
M_DAM4  EQU 8                       ; DMA Address Mode 4
M_DAM5  EQU 9                       ; DMA Address Mode 5
M_D3D EQU 10                        ; DMA Three Dimensional Mode
```